

芯伯乐®
X I N B O L E

Product Specification

XBLW SN74LS139

Dual 2-to-4 line decoder/demultiplexer

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Description

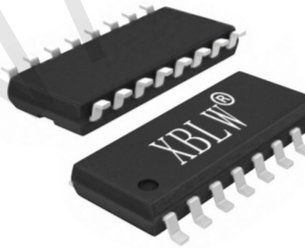
The SN74LS139 decodes two binary weighted address inputs (nA_0 , nA_1) to four mutually exclusive outputs ($n\bar{Y}_0$ to $n\bar{Y}_3$). Each decoder features an enable input ($n\bar{E}$). When $n\bar{E}$ is HIGH all outputs are forced HIGH. The enable input can be used as the data input for a 1-to-4 demultiplexer application. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

Features

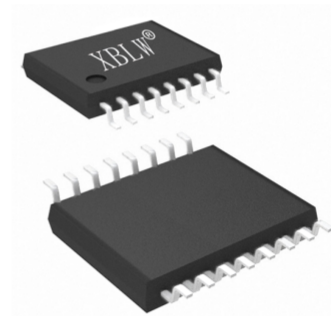
- Demultiplexing capability
- 2 independent 2-to-4 decoders
- Multifunction capability
- Suitable for memory decoding, data routing or code conversion
- Active LOW mutually exclusive outputs
- Specified from -20°C to $+85^{\circ}\text{C}$
- Packaging information: DIP-16/SOP-16/TSSOP-16
- Wide supply voltage range from 2.0 to 6.0 V



DIP-16



SOP-16



TSSOP-16

ORDERING INFORMATION

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS139N	DIP-16	74LS139N	Tube	1000Pcs/Box
XBLW SN74LS139DTR	SOP-16	74LS139	Tape	2500Pcs/Reel
XBLW SN74LS139TDTR	TSSOP-16	74LS139	Tape	3000Pcs/Reel

Block Diagram

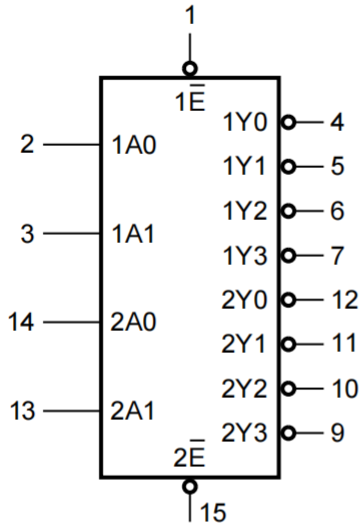


Figure 1. Logic symbol

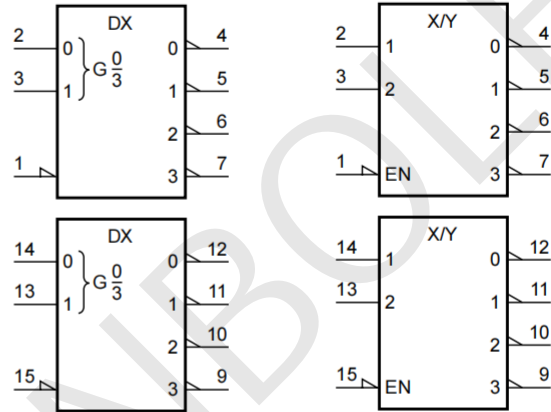


Figure 2. IEC logic symbol

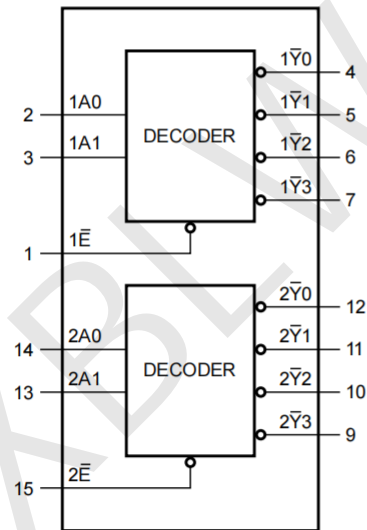


Figure 3. Functional diagram

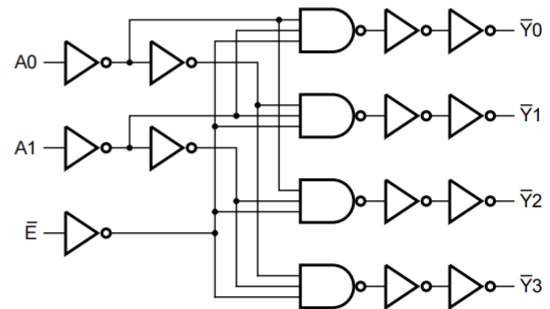
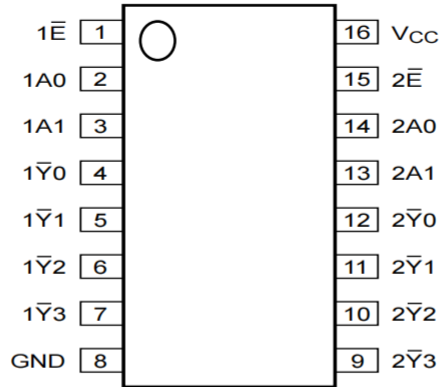


Figure 4. Logic diagram(one decodr/demultiplexer)

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	$1\bar{E}$	enable input(active LOW)
2	1A0	address input
3	1A1	address input
4	$1\bar{Y}0$	output(active LOW)
5	$1\bar{Y}1$	output(active LOW)
6	$1\bar{Y}2$	output(active LOW)
7	$1\bar{Y}3$	output(active LOW)
8	GND	ground(0V)
9	$2\bar{Y}3$	output(active LOW)
10	$2\bar{Y}2$	output(active LOW)
11	$2\bar{Y}1$	output(active LOW)
12	$2\bar{Y}0$	output(active LOW)
13	2A1	address input
14	2A0	address input
15	$2\bar{E}$	enable input(active LOW)
16	Vcc	Supply voltage

Function Table

Control	Input		Output			
$\bar{n}E$	nA1	nA0	$\bar{n}Y3$	$\bar{n}Y2$	$\bar{n}Y1$	$\bar{n}Y0$
H	X	X	H	H	H	H
L	L	L	H	H	H	L
L	L	H	H	H	L	H
L	H	L	H	L	H	H
L	H	H	L	H	H	H

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}		-0.5	+7.0	V
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	-	± 20	mA
output clamping current	I_{OK}	$V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	-	± 20	mA
output current	I_O	$V_O = -0.5V$ to $V_{CC} + 0.5V$	-	± 25	mA
supply current	I_{CC}	-	-	50	mA
ground current	I_{GND}	-	-50	-	mA
storage temperature	T_{stg}	-	-65	+150	°C
total power dissipation	P_{tot}	-	-	500	mW
soldering temperature	T_L	10s	DIP	245	°C
			SOP	250	

Note:

[1] For DIP16 packages: above 70°C the value of P_{tot} derates linearly with 12mW/K.

[2] For SOP16 packages: above 70°C the value of P_{tot} derates linearly with 8mW/K.

[3] For (T)SSOP16 packages: above 60°C the value of P_{tot} derates linearly with 5.5mW/K.

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t / \Delta V$	$V_{CC} = 2.0V$	-	-	625	ns/V
		$V_{CC} = 4.5V$	-	1.67	139	ns/V
		$V_{CC} = 6.0V$	-	-	83	ns/V
ambient temperature	T_{amb}	-	-20	-	+85	°C

Electrical Characteristics

DC Characteristics 1

($T_{amb}=25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	1.2	-	V	
		$V_{CC}=4.5\text{V}$	3.15	2.4	-	V	
		$V_{CC}=6.0\text{V}$	4.2	3.2	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	0.8	0.5	V	
		$V_{CC}=4.5\text{V}$	-	2.1	1.35	V	
		$V_{CC}=6.0\text{V}$	-	2.8	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I=V_{IH}$ or V_{IL}	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	2.0	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	4.5	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	6.0	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.98	4.32	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH}$ or V_{IL}	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	0	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	0.15	0.26	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	0.16	0.26	V
input leakage current	I_I	$V_I=V_{CC}$ or $\text{GND}; V_{CC}=6.0\text{V}$	-	-	± 0.1	μA	
OFF-state output current	I_{OZ}	$V_I=V_H$ or $V_{IL}; V_O=V_{CC}$ or $\text{GND}; V_{CC}=6.0\text{V}$	-	-	± 0.5	μA	
supply current	I_{CC}	$V_I=V_{CC}$ or $\text{GND}; I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	8.0	μA	
input capacitance	C_I	-	-	3.5	-	pF	

DC Characteristics 2

($T_{amb} = -20^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$	1.5	-	-	V	
		$V_{CC}=4.5V$	3.15	-	-	V	
		$V_{CC}=6.0V$	4.2	-	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$	-	-	0.5	V	
		$V_{CC}=4.5V$	-	-	1.35	V	
		$V_{CC}=6.0V$	-	-	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_O = -20\mu A; V_{CC} = 2.0V$	1.9	-	-	V
			$I_O = -20\mu A; V_{CC} = 4.5V$	4.4	-	-	V
			$I_O = -20\mu A; V_{CC} = 6.0V$	5.9	-	-	V
			$I_O = -4.0mA; V_{CC} = 4.5V$	3.	-	-	V
			$I_O = -5.2mA; V_{CC} = 6.0V$	845.	-	-	V
LOW-level output voltage	V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_O = 20\mu A; V_{CC} = 2.0V$	34	-	0.1	V
			$I_O = 20\mu A; V_{CC} = 4.5V$	-	-	0.1	V
			$I_O = 20\mu A; V_{CC} = 6.0V$	-	-	0.1	V
			$I_O = 4.0mA; V_{CC} = 4.5V$	-	-	0.33	V
			$I_O = 5.2mA; V_{CC} = 6.0V$	-	-	0.33	V
input leakage current	I_I	$V_i = V_{CC}$ or $GND; V_{CC} = 6.0V$	-	-	± 1.0	μA	
OFF-state output current	I_{OZ}	$V_I = V_{IH}$ or $V_{IL}; V_O = V_{CC}$ or $GND; V_{CC} = 6.0V$	-	-	± 5.0	μA	
supply current	I_{CC}	$V_i = V_{CC}$ or $GND; I_O = 0A; V_{CC} = 6.0V$	-	-	80	μA	

AC Characteristics 1

($T_{amb}=25^{\circ}C$, $GND=0V$, $C_L=50pF$ unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Propagation delay	t_{pd}	nAn to n \bar{Y} n see Figure6 ^[1]	$V_{CC}=2.0V$	-	39	145	ns
			$V_{CC}=4.5V$	-	14	29	ns
			$V_{CC}=5.0V; C_L=15pF$	-	11	-	ns
		n \bar{E} to n \bar{Y} n see Figure7 ^[2]	$V_{CC}=2.0V$	-	33	135	ns
			$V_{CC}=4.5V$	-	12	27	ns
			$V_{CC}=5.0V; C_L=15pF$	-	10	-	ns
transition time	t_t	n \bar{Y} n; see Figure6 and Figure7 ^[2]	$V_{CC}=2.0V$	-	19	75	ns
			$V_{CC}=4.5V$	-	7	15	ns
			$V_{CC}=6.0V$	-	6	13	ns
power dissipation capacitance	C_{PD}	$C_L=50pF; f=1MHz; V_I=GND$ to V_{CC} ^[3]	-	42	-	pF	

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_t is the same as t_{THL} and t_{TLH} .

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in uW).

$P_D=C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$ where:

f_i =input frequency in MHz;

f_o =output frequency in MHz;

C_L =output load capacitance in pF;

V_{CC} =supply voltage in V;

N =number of inputs switching;

$\sum(C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.

AC Characteristics 2

($T_{amb} = -20^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $GND = 0V$, $C_L = 50\text{pF}$, unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Propagation delay	t_{pd}	nAn to n \bar{Y} n see Figure6 ^[1]	$V_{CC}=2.0V$	-	-	180	ns
			$V_{CC}=4.5V$	-	-	36	ns
			$V_{CC}=6.0V$	-	-	31	ns
		n \bar{E} to n \bar{Y} n see Figure7 ^[1]	$V_{CC}=2.0V$	-	-	170	ns
			$V_{CC}=4.5V$	-	-	34	ns
			$V_{CC}=6.0V$	-	-	29	ns
transition time	t_t	n \bar{Y} n; see Figure6 and Figure7 ^[2]	$V_{CC}=2.0V$	-	-	95	ns
			$V_{CC}=4.5V$	-	-	19	ns
			$V_{CC}=6.0V$	-	-	16	ns

Note:

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] t_t is the same as t_{THL} and t_{TLH} .

Testing Circuit

AC Testing Circuit

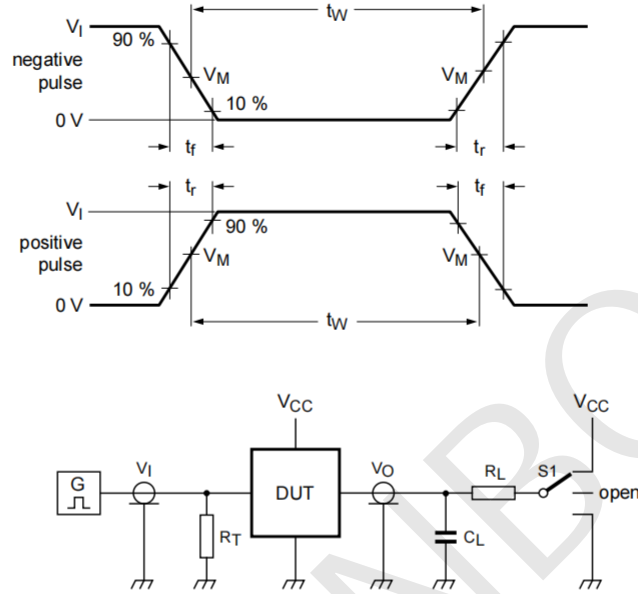


Figure 5. Test circuit for measuring switching times

Definitions for test circuit:

C_L =Load capacitance including jig and probe capacitance.

R_T =Termination resistance should be equal to the output impedance Z_o of the pulse generator. R_L =Load resistance.

$S1$ =Test selection switch.

AC Testing Waveforms

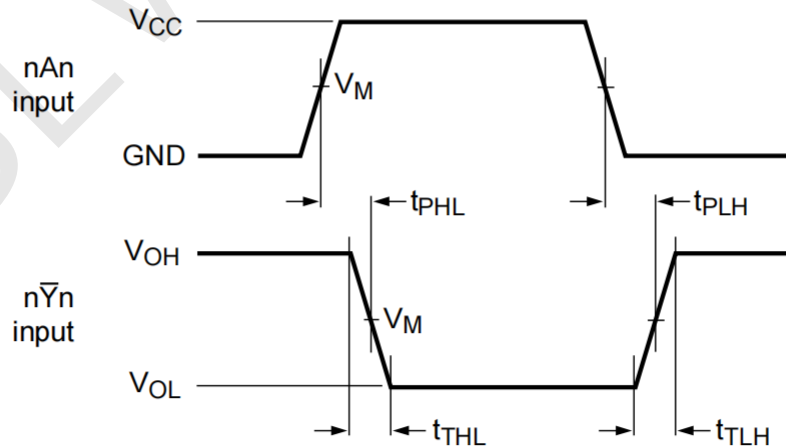


Figure 6. Propagation delay input (nAn) to output ($n\bar{Y}n$) and transition time output ($n\bar{Y}n$)

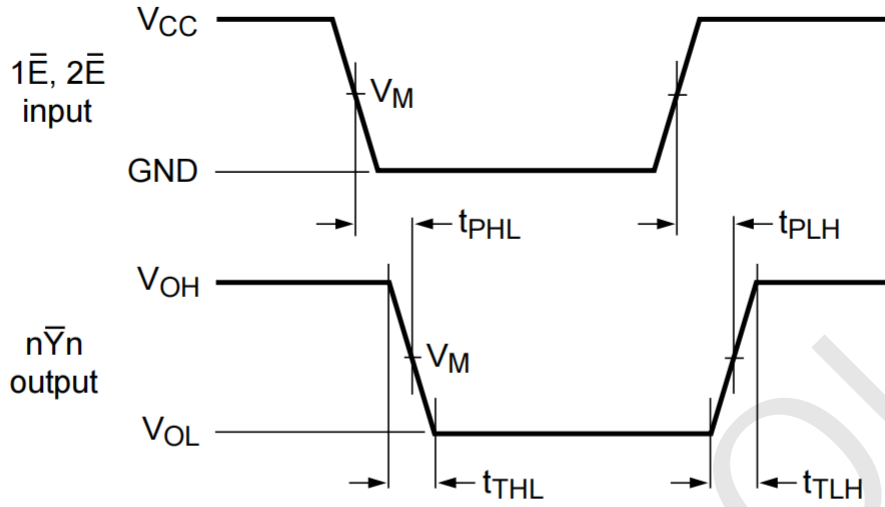


Figure 7. Propagation delay enable input ($\bar{n}E$) to output ($\bar{n}Y_n$) and transition time output ($\bar{n}Y_n$)

Measurement Points

Type	Input	Output
	V_M	V_M
SN74LS139	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

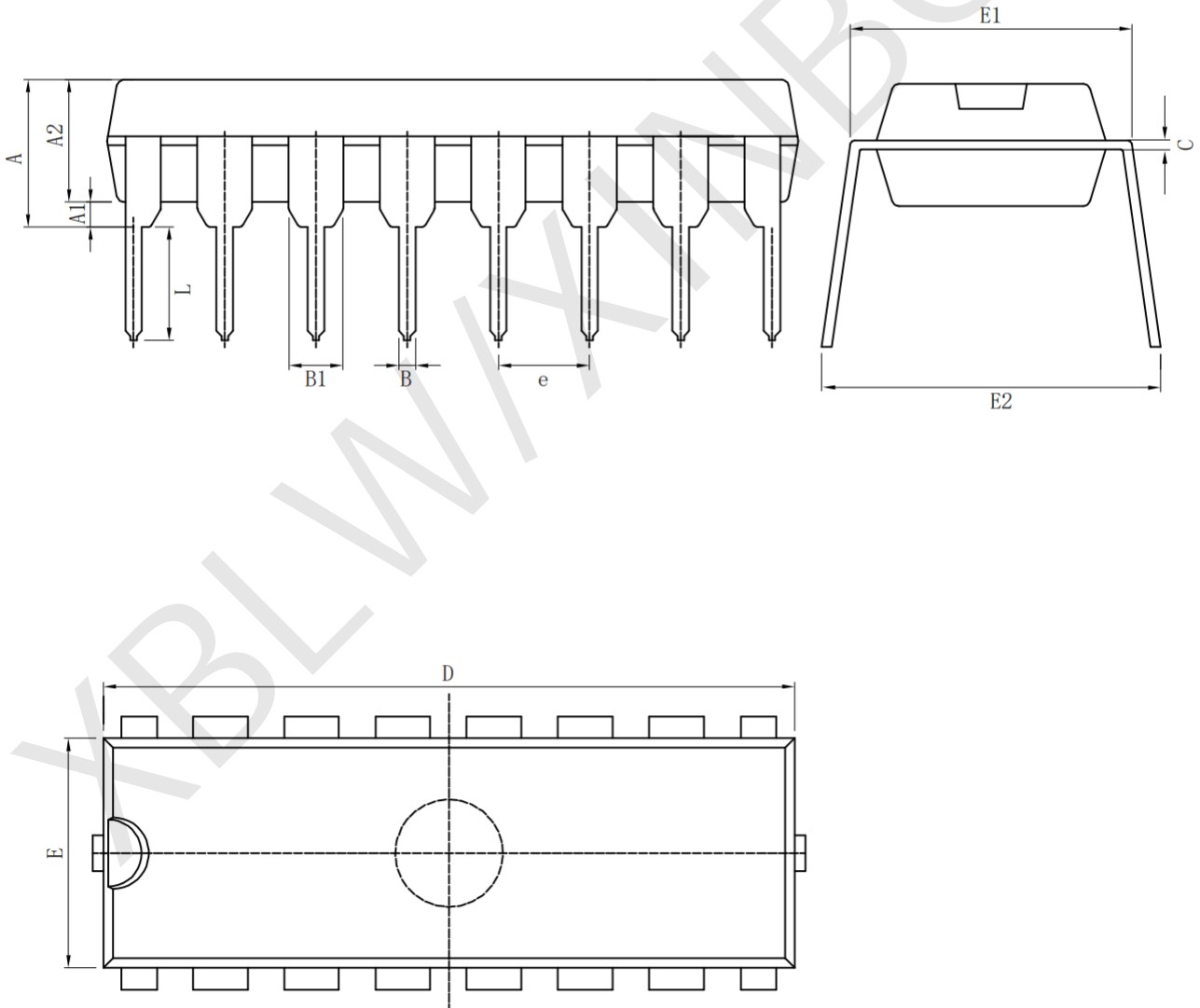
Test Data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
SN74LS139	V_{CC}	6.0ns	15pF, 50pF	1K Ω	open	GND	V_{CC}

Package Information

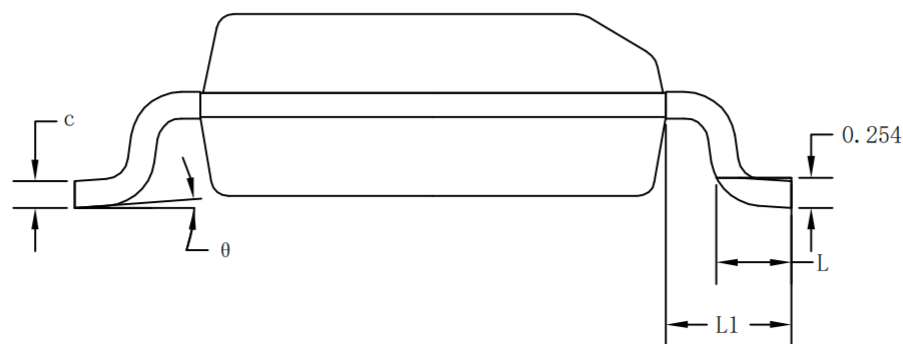
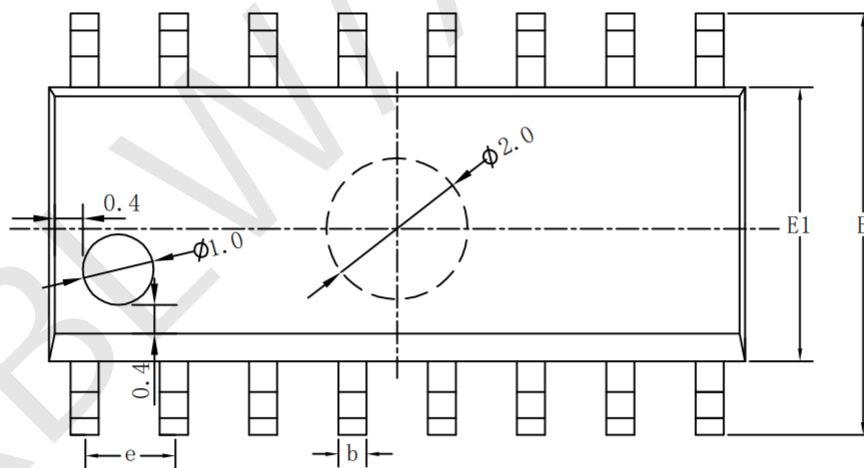
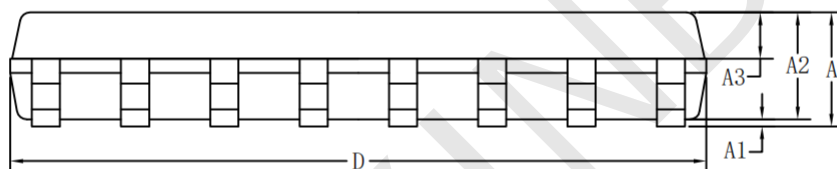
· DIP-16

Symbol	Size	Dimensions In Millimeters		Symbol	Size	Dimensions In Inches	
		Min(mm)	Max(mm)			Min(in)	Max(in)
A		3.710	4.310	A		0.146	0.170
A1		0.510		A1		0.020	
A2		3.200	3.600	A2		0.126	0.142
B		0.380	0.570	B		0.015	0.022
B1		1.524 (BSC)		B1		0.060 (BSC)	
C		0.204	0.360	C		0.008	0.014
D		18.80	19.20	D		0.740	0.756
E		6.200	6.600	E		0.244	0.260
E1		7.320	7.920	E1		0.288	0.312
e		2.540 (BSC)		e		0.100 (BSC)	
L		3.000	3.600	L		0.118	0.142
E2		8.400	9.000	E2		0.331	0.354



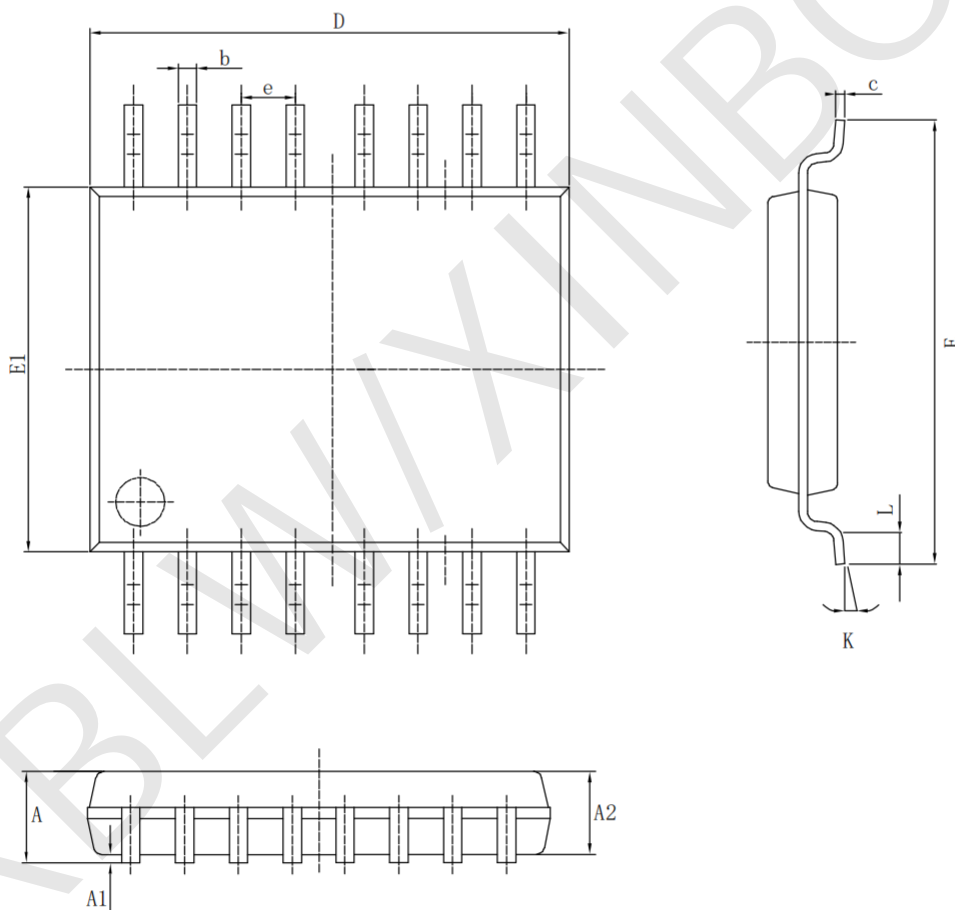
· SOP-16

Symbol	Size	Dimensions In Millimeters			Symbol	Size	Dimensions In Inches		
		Min (mm)	Nom (mm)	Max (mm)			Min (in)	Nom (in)	Max (in)
A		1.500	1.600	1.700	A		0.059	0.063	0.067
A1		0.100	0.150	0.250	A1		0.004	0.006	0.010
A2		1.400	1.450	1.500	A2		0.055	0.057	0.059
A3		0.600	0.650	0.700	A3		0.024	0.026	0.028
b		0.300	0.400	0.500	b		0.012	0.016	0.020
c		0.150	0.200	0.250	c		0.006	0.008	0.010
D		9.800	9.900	10.00	D		0.386	0.390	0.394
E		5.800	6.000	6.200	E		0.228	0.236	0.244
E1		3.850	3.900	3.950	E1		0.152	0.154	0.156
e		1.27 (BSC)			e		0.050 (BSC)		
L		0.500	0.600	0.700	L		0.020	0.024	0.028
L1		1.05 (BSC)			L1		0.041 (BSC)		
θ		0°	4°	8°	θ		0°	4°	8°



· TSSOP-16

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.480	E1	0.169	0.176
e	0.65 (BSC)		e	0.0256 (BSC)	
K	0°	8°	K	0°	8°
L	0.450	0.750	L	0.018	0.030



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